

74HC2G34-Q100; 74HCT2G34-Q100

Dual buffer gate

Rev. 2 — 4 November 2013

Product data sheet

1. General description

The 74HC2G34-Q100; 74HCT2G34-Q100 is a dual buffer. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40°C to $+85^{\circ}\text{C}$ and from -40°C to $+125^{\circ}\text{C}$
- Input levels:
 - ◆ For 74HC2G34-Q100: CMOS level
 - ◆ For 74HCT2G34-Q100: TTL level
- Wide supply voltage range from 2.0 V to 6.0 V
- Complies with JEDEC standard no. 7A
- High noise immunity
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\ \Omega$)
- Low power dissipation
- Balanced propagation delays
- Unlimited input rise and fall times

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC2G34GW-Q100	-40°C to $+125^{\circ}\text{C}$	SC-88	plastic surface-mounted package; 6 leads	SOT363
74HCT2G34GW-Q100				
74HC2G34GV-Q100	-40°C to $+125^{\circ}\text{C}$	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457
74HCT2G34GV-Q100				



4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74HC2G34GW-Q100	PA
74HCT2G34GW-Q100	UA
74HC2G34GV-Q100	P34
74HCT2G34GV-Q100	U34

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

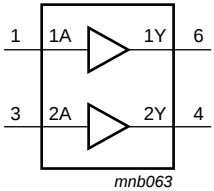


Fig 1. Logic symbol

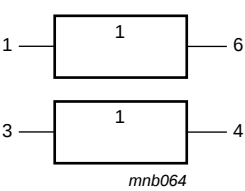


Fig 2. IEC logic symbol

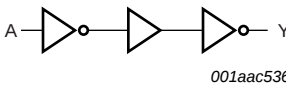


Fig 3. Logic diagram (one gate)

6. Pinning information

6.1 Pinning

74HC2G34-Q100
74HCT2G34-Q100

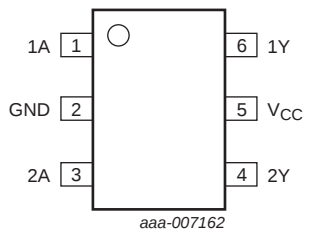


Fig 4. Pin configuration

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1A	1	data input
GND	2	ground (0 V)
2A	3	data input
2Y	4	data output
V _{CC}	5	supply voltage
1Y	6	data output

7. Functional description

Table 4. Function table^[1]

Input	Output
nA	nY
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	^[1] -	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V	^[1] -	±20	mA
I _O	output current	V _O = -0.5 V to V _{CC} + 0.5 V	^[1] -	±25	mA
I _{CC}	supply current		^[1] -	+50	mA
I _{GND}	ground current		^[1] -	-50	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation		^[2] -	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SC-88 and SC-74 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Type 74HC2G34-Q100						
V _{CC}	supply voltage		2.0	5.0	6.0	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	°C
t _r	rise time	except for Schmitt trigger inputs				
		V _{CC} = 2.0 V	-	-	1000	ns
		V _{CC} = 4.5 V	-	-	500	ns
		V _{CC} = 6.0 V	-	-	400	ns
t _f	fall time	except for Schmitt trigger inputs				
		V _{CC} = 2.0 V	-	-	1000	ns
		V _{CC} = 4.5 V	-	-	500	ns
		V _{CC} = 6.0 V	-	-	400	ns
Type 74HCT2G34-Q100						
V _{CC}	supply voltage		4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	°C
t _r	rise time	except for Schmitt trigger inputs				
		V _{CC} = 4.5 V	-	-	500	ns
t _f	fall time	except for Schmitt trigger inputs				
		V _{CC} = 4.5 V	-	-	500	ns

10. Static characteristics

Table 7. Static characteristics for 74HC2G34-Q100

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	V

Table 7. Static characteristics for 74HC2G34-Q100 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 2.0\ \text{V}$	1.9	2.0	-	V
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 4.5\ \text{V}$	4.4	4.5	-	V
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 6.0\ \text{V}$	5.9	6.0	-	V
		$I_O = -4.0\ \text{mA}$; $V_{CC} = 4.5\ \text{V}$	4.18	4.32	-	V
		$I_O = -5.2\ \text{mA}$; $V_{CC} = 6.0\ \text{V}$	5.68	5.81	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 2.0\ \text{V}$	-	0	0.1	V
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 4.5\ \text{V}$	-	0	0.1	V
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 6.0\ \text{V}$	-	0	0.1	V
		$I_O = 4.0\ \text{mA}$; $V_{CC} = 4.5\ \text{V}$	-	0.15	0.26	V
		$I_O = 5.2\ \text{mA}$; $V_{CC} = 6.0\ \text{V}$	-	0.16	0.26	V
I_I	input leakage current	$V_I = \text{GND}$ or V_{CC} ; $V_{CC} = 6.0\ \text{V}$	-	-	± 0.1	μA
I_{CC}	supply current	$V_I = \text{GND}$ or V_{CC} ; $I_O = 0\ \text{A}$; $V_{CC} = 6.0\ \text{V}$	-	-	1.0	μA
C_I	input capacitance		-	1.5	-	pF
$T_{amb} = -40\ ^\circ\text{C}$ to $+85\ ^\circ\text{C}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 2.0\ \text{V}$	1.5	-	-	V
		$V_{CC} = 4.5\ \text{V}$	3.15	-	-	V
		$V_{CC} = 6.0\ \text{V}$	4.2	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.0\ \text{V}$	-	-	0.5	V
		$V_{CC} = 4.5\ \text{V}$	-	-	1.35	V
		$V_{CC} = 6.0\ \text{V}$	-	-	1.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 2.0\ \text{V}$	1.9	-	-	V
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 4.5\ \text{V}$	4.4	-	-	V
		$I_O = -20\ \mu\text{A}$; $V_{CC} = 6.0\ \text{V}$	5.9	-	-	V
		$I_O = -4.0\ \text{mA}$; $V_{CC} = 4.5\ \text{V}$	4.13	-	-	V
		$I_O = -5.2\ \text{mA}$; $V_{CC} = 6.0\ \text{V}$	5.63	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 2.0\ \text{V}$	-	-	0.1	V
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 4.5\ \text{V}$	-	-	0.1	V
		$I_O = 20\ \mu\text{A}$; $V_{CC} = 6.0\ \text{V}$	-	-	0.1	V
		$I_O = 4.0\ \text{mA}$; $V_{CC} = 4.5\ \text{V}$	-	-	0.33	V
		$I_O = 5.2\ \text{mA}$; $V_{CC} = 6.0\ \text{V}$	-	-	0.33	V
I_I	input leakage current	$V_I = \text{GND}$ or V_{CC} ; $V_{CC} = 6.0\ \text{V}$	-	-	± 1.0	μA
I_{CC}	supply current	$V_I = \text{GND}$ or V_{CC} ; $I_O = 0\ \text{A}$; $V_{CC} = 6.0\ \text{V}$	-	-	10.0	μA

Table 7. Static characteristics for 74HC2G34-Q100 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	V
		V _{CC} = 4.5 V	3.15	-	-	V
		V _{CC} = 6.0 V	4.2	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	-	0.5	V
		V _{CC} = 4.5 V	-	-	1.35	V
		V _{CC} = 6.0 V	-	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 2.0 V	1.9	-	-	V
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	-	-	V
		I _O = -20 µA; V _{CC} = 6.0 V	5.9	-	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.7	-	-	V
		I _O = -5.2 mA; V _{CC} = 6.0 V	5.2	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 2.0 V	-	-	0.1	V
		I _O = 20 µA; V _{CC} = 4.5 V	-	-	0.1	V
		I _O = 20 µA; V _{CC} = 6.0 V	-	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	-	0.4	V
I _I	input leakage current	V _I = GND or V _{CC} ; V _{CC} = 6.0 V	-	-	±1.0	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 6.0 V	-	-	20.0	µA

Table 8. Static characteristics for 74HCT2G34-Q100

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	4.5	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	4.18	4.32	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 4.5 V	-	0	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	V
I _I	input leakage current	V _I = GND or V _{CC} ; V _{CC} = 5.5 V	-	-	±0.1	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 5.5 V	-	-	1.0	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 2.1 V; V _{CC} = 4.5 V to 5.5 V; I _O = 0 A	-	-	300	µA
C _I	input capacitance		-	1.5	-	pF

Table 8. Static characteristics for 74HCT2G34-Q100 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	-	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	4.13	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 4.5 V	-	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	-	0.33	V
I _I	input leakage current	V _I = GND or V _{CC} ; V _{CC} = 5.5 V	-	-	±1.0	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 5.5 V	-	-	10.0	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 2.1 V; V _{CC} = 4.5 V to 5.5 V; I _O = 0 A	-	-	375	µA
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	-	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.7	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 4.5 V	-	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	-	0.4	V
I _I	input leakage current	V _I = GND or V _{CC} ; V _{CC} = 5.5 V	-	-	±1.0	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 5.5 V	-	-	20.0	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 2.1 V; V _{CC} = 4.5 V to 5.5 V; I _O = 0 A	-	-	410	µA

11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max (85 °C)	Max (125 °C)	
74HC2G34-Q100									
t _{pd}	propagation delay	nA to nY; see Figure 5 [1]							
		V _{CC} = 2.0 V; C _L = 50 pF	-	29	75	-	95	125	ns
		V _{CC} = 4.5 V; C _L = 50 pF	-	9	15	-	19	25	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	8	13	-	16	20	ns
t _t	transition time	nY; see Figure 5 [2]							
		V _{CC} = 2.0 V; C _L = 50 pF	-	18	75	-	95	125	ns
		V _{CC} = 4.5 V; C _L = 50 pF	-	6	15	-	19	25	ns
		V _{CC} = 6.0 V; C _L = 50 pF	-	5	13	-	16	20	ns
C _{PD}	power dissipation capacitance	V _I = GND to V _{CC} [3]	-	10	-	-	-	-	pF
74HCT2G34-Q100									
t _{pd}	propagation delay	nA to nY; see Figure 5 [1]							
		V _{CC} = 4.5 V; C _L = 50 pF	-	10	18	-	23	29	ns
t _t	transition time	nY; see Figure 5 [2]							
		V _{CC} = 4.5 V; C _L = 50 pF	-	6	15	-	19	25	ns
C _{PD}	power dissipation capacitance	V _I = GND to V _{CC} – 1.5 V [3]	-	9	-	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}

[2] t_t is the same as t_{TLH} and t_{THL}

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

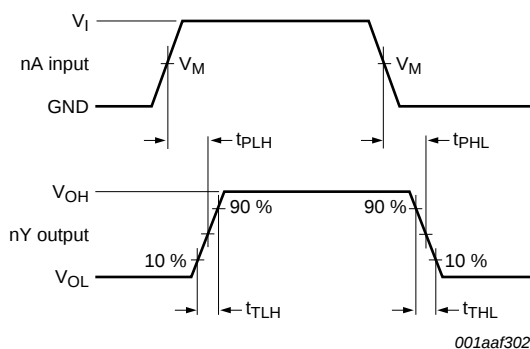
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

12. Waveforms



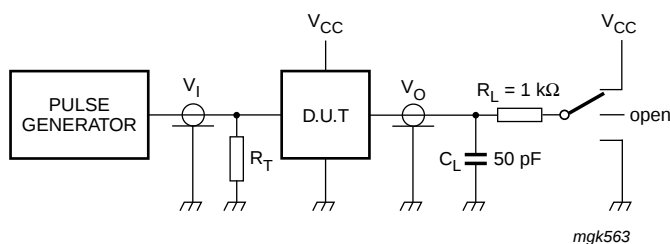
Measurement points are given in [Table 10](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. The data input (nA) to output (nY) propagation delays and output transition times

Table 10. Measurement points

Type	Input			Output
	V_M	V_I	$t_r = t_f$	V_M
74HC2G34-Q100	$0.5V_{CC}$	GND to V_{CC}	6.0 ns	$0.5V_{CC}$
74HCT2G34-Q100	1.3 V	GND to 3.0 V	6.0 ns	1.3 V



Test data is given in [Table 11](#).

Definitions test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 6. Test circuit for measuring switching times

Table 11. Test data

Type	Input		Test
	V_I	t_r, t_f	t_{PHL}, t_{PLH}
74HC2G34-Q100	GND to V_{CC}	6 ns	open
74HCT2G34-Q100	GND to 3.0 V	6 ns	open

13. Package outline

Plastic surface-mounted package; 6 leads

SOT363

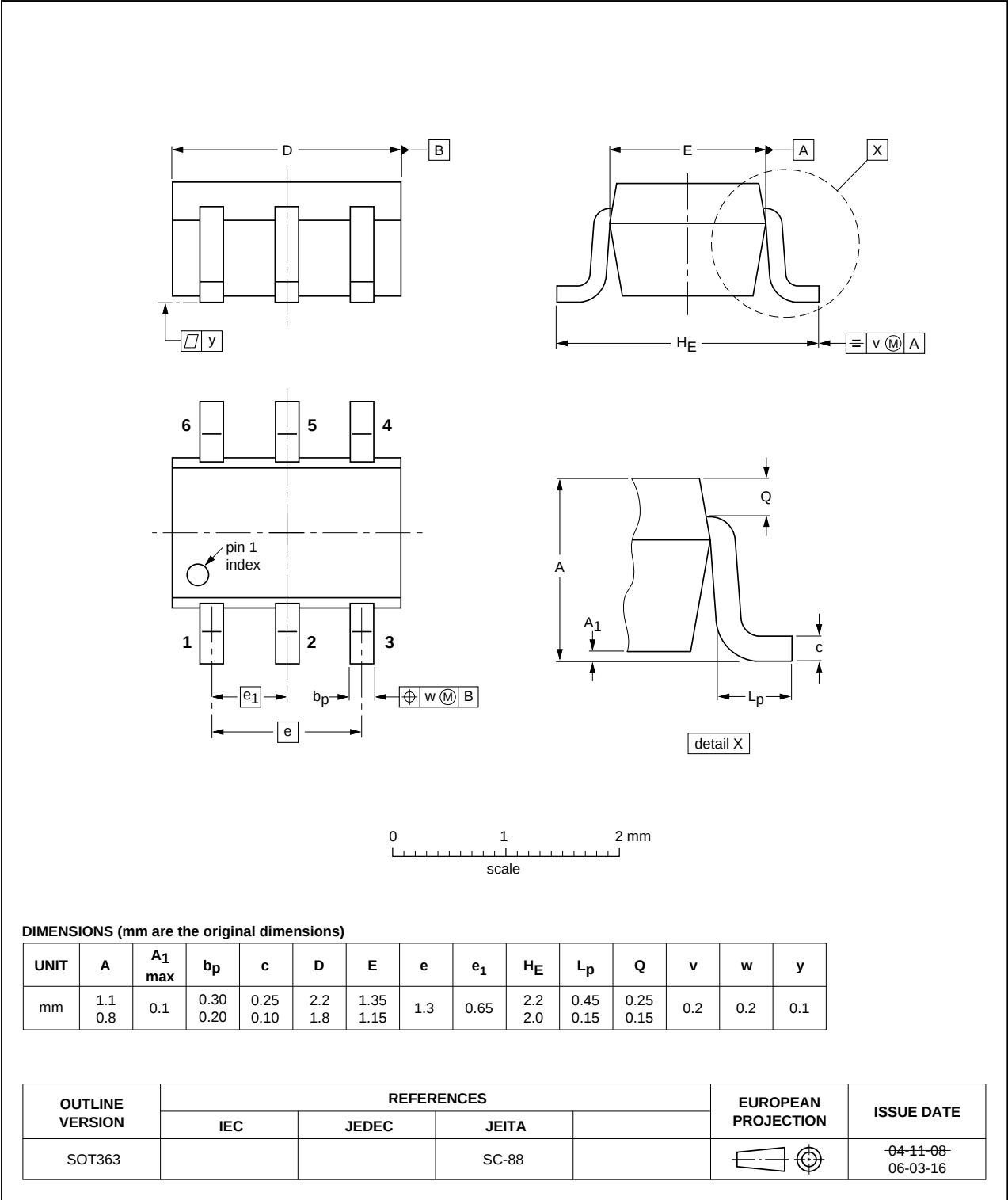


Fig 7. Package outline SOT363 (SC-88)

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

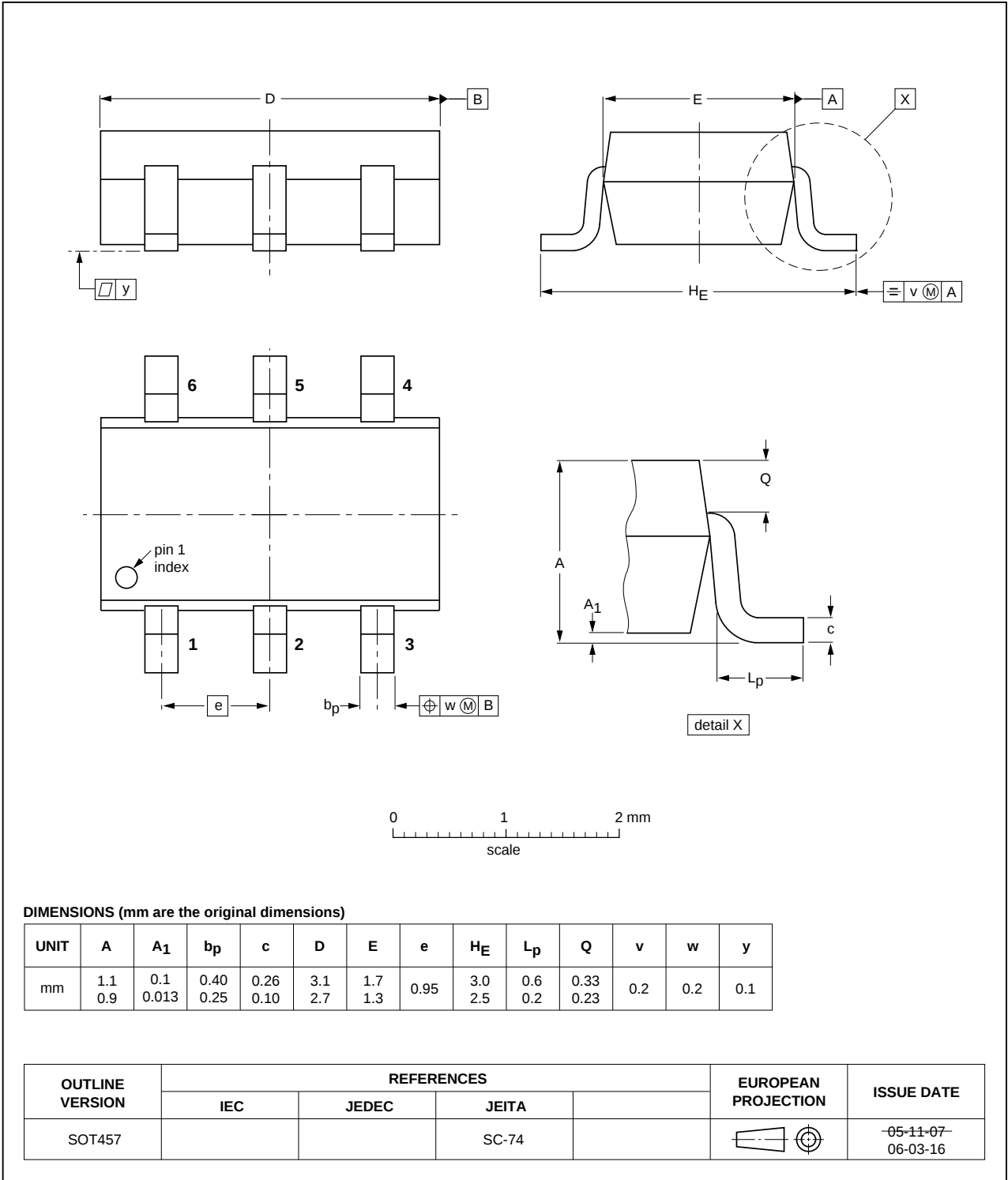


Fig 8. Package outline SOT457 (SC-74)

14. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
DUT	Device Under Test

15. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT2G34_Q100 v.2	20131104	Product data sheet	-	74HC_HCT2G34_Q100 v.1
Modifications:				
• Added type number 74HC2G34GW and 74HCT2G34GW (SOT363)				
74HC_HCT2G34_Q100 v.1	20130417	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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18. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Marking	2
5	Functional diagram	2
6	Pinning information	2
6.1	Pinning	2
6.2	Pin description	3
7	Functional description	3
8	Limiting values	3
9	Recommended operating conditions	4
10	Static characteristics	4
11	Dynamic characteristics	8
12	Waveforms	9
13	Package outline	10
14	Abbreviations	12
15	Revision history	12
16	Legal information	13
16.1	Data sheet status	13
16.2	Definitions	13
16.3	Disclaimers	13
16.4	Trademarks	14
17	Contact information	14
18	Contents	15

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